



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK® MLP66</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HRS./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
Bond Integrity	285	122 500	200 °C + N2	0	0.00
HAST	958	95 800	130 °C, 85 % RH	0	0.00
High Temp. Storage	1312	1 027 214	175 °C to 200 °C	0	0.00
Pressure Pot	2329	223 584	121 °C, 15 PSIG	0	0.00
Solder Dunk	864	2592	260 °C, 10 s	0	0.00
Solder Ability	70	560	883 M2003	0	0.00
Temp. Cycle	2371	1 684 500	-65 °C to +150 °C	0	0.00